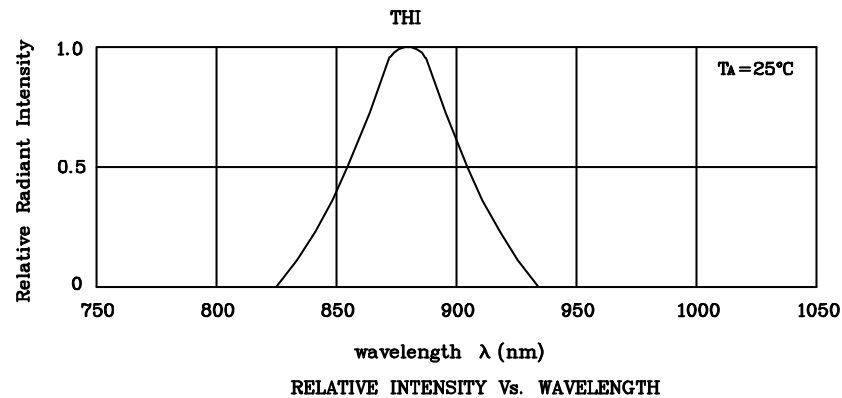
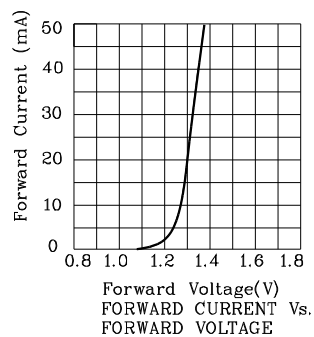
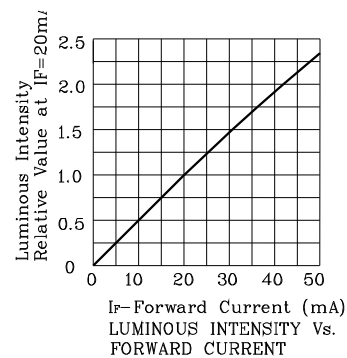
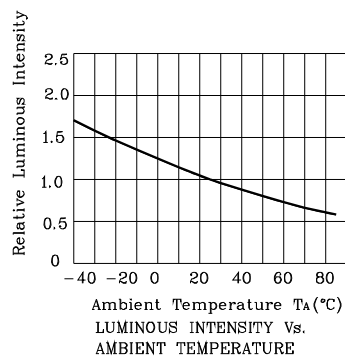
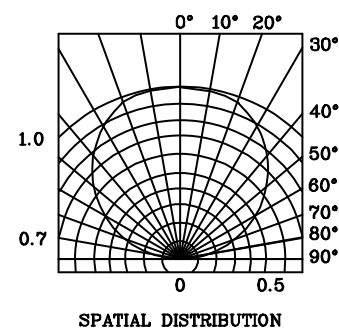
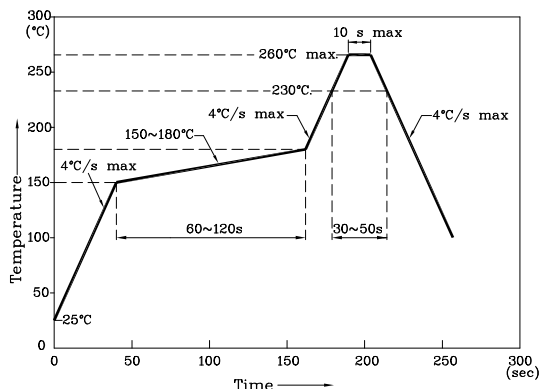




❖ **THI**



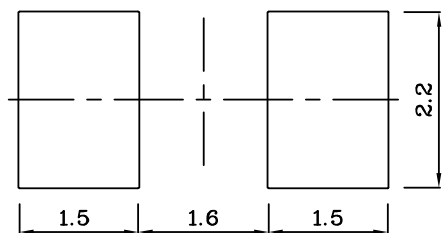
Reflow Soldering Profile For Lead-free SMT Process.



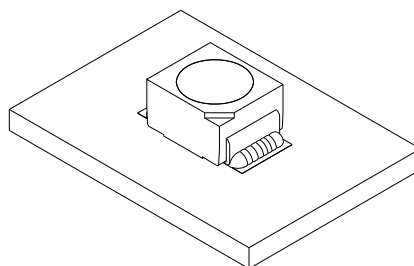
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C~260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

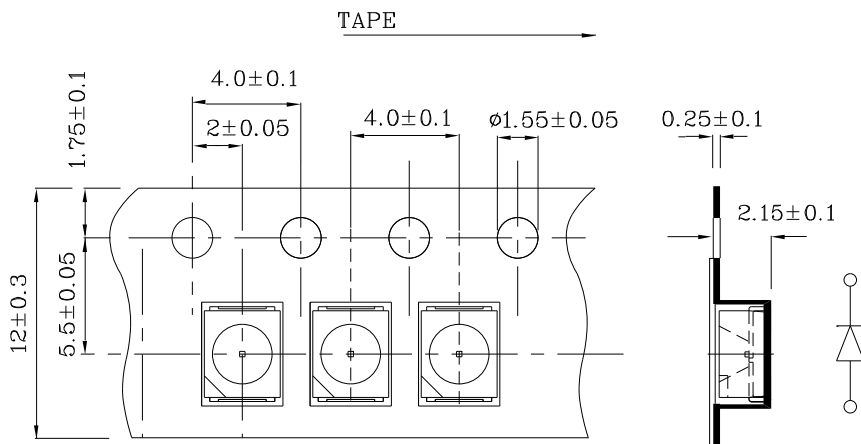
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ±0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

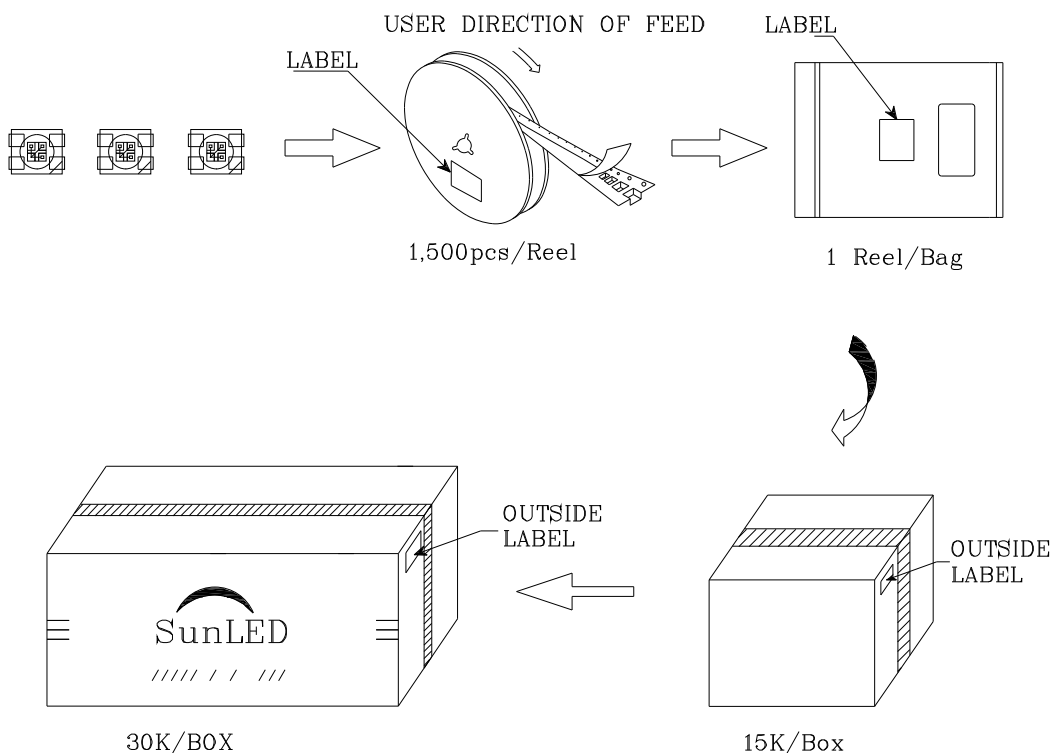
If special sorting is required (e.g. binning based on forward voltage or radiant intensity / luminous flux), the typical accuracy of the sorting process is as follows:

1. Radiant Intensity / Luminous Flux: +/-15%
2. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

ZTHI45W



		Q.C. Q C XX XX XXXX PASSED
P/NO : Zxxx45x		
QTY : 1,500 pcs		CODE: XXX
S/N : XX		
LOT NO :		
 XXXXXXXXXXXXXXXXXXXXXXXX		
RoHS Compliant		